Product / Package Information

Package:	WLCSP
Body Size (mm):	
I/O Count:	8
Terminal Finish	SnAgCu

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	1.57 E-03	100.00	1000000	61.77	617652

Wafer Bumps

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	7.98E-04	95.50	955000	31.41	314090
Tin & its alloys	Silver	7440-22-4	3.18E-05	3.80	38000	1.25	12498
Tin & its alloys	Copper	7440-50-8	5.85 E-06	0.70	7000	0.23	2302
Subtotal			8.36E-04	100.00	1000000	32.89	328890

UBM / Redistribution Layers

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	1.04 E-04	99.73	997296	4.09	40915
Other inorganic materials	Titanium	7440-32-6	2.82 E-07	0.27	2704	0.01	111
Subtotal			1.04E-04	100.00	1000000	4.10	41025

Polyimide

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other organic materials	Photosensitive Polyimide Resin	Proprietary		30-60			
Other organic materials	Acrylate Ester	Proprietary		5-10			
Others	Proprietary Ingredient(s)	Proprietary		1-5			
Subtotal			3.16 E-05	100	1000000	1.24	12433

	Weight (g)	Percentage (%)	PPM
Package Totals	**2.54 E-03**	**100.00**	**1000000**

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

ADI Proprietary

ANALOG DEVICES